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Thermally Conductive Tape 9892FR

Preliminary Technical Data Page

April 2000

Product Description

3M TMThermally Conductive Tape 9892FR consists of a highly conformable pressure-sensitive film composed of an acrylic adhesive filled with ceramic particles and supported on a protective release liner. It features a unique combination of attributes that include ease-of-use, high thermal conductivity, good dielectric properties and high bond strength (with reworkability).

3M TMThermally Conductive Tape 9892FR is designed for bonding heat sinks to a wide variety of heat-generating electronic components – for example, IC packages, circuit boards and plasma-type flat-panel displays (PDPs) – and can easily be die-cut to meet specific application requirements. Permanent yet re-workable bonds are achieved at room temperature in just seconds without the need for an extended curing cycle and mechanical fixturing. Due to the absence of a stiff carrier as part of the tape construction, 3M TM Thermally Conductive Tape 9892FR provides excellent conformability to non-flat or otherwise irregular surfaces and acts as an effective gap-filler. Improved surface contact helps achieve high bond strength and low thermal interface resistance between the two substrates without the use of clamps, brackets or screws. In many applications, the high dielectric strength of 3M TMThermally Conductive Tape 9892FR will also allow the elimination of discrete electrical insulation layers.

Product Construction

Tape Color	White	
Adhesive Type	Acrylic	
Adhesive Thickness	1.0 mm	
Filler Type	Ceramic	
Release Liner Type	Silicone-Treated Polyester	
Release Liner Thickness	50 μm	

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Typical Properties and Performance Characteristics

Note: The following technical information should be considered representative or typical only and should not be used for specification purposes.

Property	Value	
Density (g/cm³)		1.6
Thermal Conductivity (W/m-K) (by Kemtherm QTM-D3)		0.7
Hardness (Asker-C)		44
Maximum Use-Temperature (°C)		80
Flame-Retardancy Rating (UL-94)		V-2 (File No. E176845)
00° Real Adhasian (N/am)	on Aluminum	5
90°-Peel Adhesion (N/cm)	on Glass	4
Shear adhesion (N/cm²)	Aluminum to Glass	38
Dielectric Strength (kV/mm)		15.7
Dielectric Constant	at 50 Hz	5.1
	at 1 kHz	4.9
	at 1 MHz	4.5
Shelf Life (at 25°C)		6 months
Outgassing (Total Mass-Loss during 100°C/30 min. Exposure)		0.17 %

Available Sizes

Standard Rolls: 280 mm wide by 33 m long

Custom Sizes: Contact your local 3M sales representative for information and availability of custom sizes (width and length or sheet format) or die-cut parts of tape 9892FR

Application Techniques

- 1.) 3M TMThermally Conductive Tape 9892FR is a homogeneous adhesive film supported on a protective release liner. Do not remove this release liner prior to application of the tape to the surface of one of the substrates; the product is not intended to be handled as a free-standing film. Avoid touching the exposed surface of the tape as this may deposit finger oils and introduce wrinkles.
- 2.) Substrate surfaces should be clean and dry prior to tape application. Isopropyl alcohol (isopropanol) applied with a lint-free wipe or swab should be adequate for removing surface contamination such as dust or finger prints. Do not use "denatured alcohol" or glass cleaners, which often contain oily components. Allow the surface to dry for several minutes applying the tape.

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More aggressive solvents (such as acetone, methyl ethyl ketone (MEK) or toluene) may be required to remove heavier contamination (grease, machine oils, solder flux, etc.) but should be followed by a final isopropanol wipe as described above.

Some molded-plastic electronic packages may be heavily contaminated with low-surface-energy mold-release agents and may require abrasive action and/or priming to make them amenable to bonding.

Note: Be sure to read and follow the manufacturers' precautions and directions when using primers and solvents.

- 3.) With the release liner still in place, apply the tape to the surface of one of the substrates in a manner that will avoid or minimize air entrapment; a roller or other lamination system is recommended. Tape and substrate temperatures at application should exceed 15° C (60° F) to prevent the tape from becoming too stiff and losing its conformability.
- 4.) Remove the release liner to expose the second face of the adhesive tape.
- 5.) Align the second substrate with respect to the first and press the two parts together (or use a roller if one of the substrates is flexible) for a few seconds. Optimal thermal and mechanical performance will be obtained when the adhesive entirely wets both substrates surfaces and displaces all remaining air from the interfacial region. The pressure and time necessary to achieve this condition will depend on the roughness of one or both surfaces, the degree of co-planarity between the two surfaces, as well as the stiffness of the substrates; heating the parts to $70-100^{\circ}\text{C}$ ($158^{\circ}-212^{\circ}\text{F}$) will help reduce the required pressure and process time.
- 6.) Reworking the bond by mechanically separating the parts, using torque action for rigid parts and peel if at least one is flexible. Remove the adhesive by rubbing it with an abrasive pad, clean up the site and apply new adhesive. The force required to separate the parts and remove the adhesive can be reduced by weakening the adhesive, either by heating it to $70-100^{\circ}\text{C}$ ($158^{\circ}-212^{\circ}\text{F}$) or applying a solvent such as acetone or MEK.

General Information

Product	Thickness (mm)	Thermal Conductivity (W/m-K)	Typical applications	
Thermally Conductive Tapes				
9882	0.051	0.45	Applications requiring thin bonding with good	
9885	0.127	0.45	thermal transfer; CPU, flex circuit and power	
9890	0.25	0.45	transformer bonding to heat sinks and other cooling devices.	
9892FR	1.0	0.70	Applications requiring gap filling and bonding with good thermal transfer; plasma display, IC packages and PCB bonding to heat sinks, metal cases and other cooling devices.	
Thermally Conductive Pads				
5507	0.5 to 2.5	2.5	Applications requiring gap filling and superior thermal performance without bonding. IC package	
5507S	0.25, 0.5 to 2.5	2.5	and PCB thermal interfacing with heat sinks or other cooling devices and metal cases.	

Product selection table for 3M TMThermally Conductive Materials

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Application Ideas	3M TM Thermally Conductive Tape 9892FR is designed to provide bonding and preferential heat-transfer path between heat-generating devices (such as IC packages, printed circuit boards and plasma displays) and cooling devices (e.g., heat sinks, metal cases and frames). The acrylate chemistry renders tape 9892FR extremely soft and compliant, allowing the tape to conform intimately to non-flat substrates, even at moderate pressures.		
For Additional Information	To request additional product information or to arrange for sales assistance, call toll free 1-800-362-3550. Address correspondence to 3M Bonding Systems Division, 3M Center, Building 220-7E-01, St. Paul, MN 55144-1000. Our fax number is 651-733-9175. In Canada, phone: 1-800-364-3577. In Puerto Rico, phone: 1-809-750-3000. In Mexico, phone 5-728-2180.		
Certification/ Recognition	MSDS: 3M has not prepared a MSDS for this product which is not subject to the MSDS requirements of the Occupational Safety and Health Administration's Hazard Communication Standard, 29 C.F.R. 1910.1200(b)(6)(v). When used under reasonable conditions or in accordance with the 3M directions for use, the product should not present a health and safety hazard. However, use or processing of the product in a manner not in accordance with the directions for use may affect its performance and present potential health and safety hazards.		
	TSCA: This product is defined as an article under the Toxic Substances Control Act and therefore, it is exempt from inventory listing requirements. UL: This product has been recognized by Underwriters Laboratories Inc. under Standard UL-94 (File No. E176845). For further information of the recognization including the card, please use the Fax-On-		
Important Notice	Demand system @ 1-800 3M MAKES NO WARRANTIES, EXPRESSED OR IMPLIED, INCLUDING, BUT NOT LIMITED TO, ANY IMPLIED WARRANTY OF MECHANTABILITY OR FITNESS FOR A PARTICULAR PURPOSE. User is responsible for determining whether the 3M product is fit for a particular purpose and suitable for user's method of application. Please remember that many factors can affect the use and performance of a 3M product in a particular application. The materials to be bonded with the product, the surface preparation of those materials, the product selected for use, the conditions in which the product is used, and the time and environmental conditions in which the product is expected to perform are among the many factors that can affect the use and performance of a 3M product. Given the variety of factors that can affect the use and performance of a 3M product, some of which are uniquely within the user's knowledge and control, it is essential that the user evaluate the 3M product to determine whether it is fit for a particular purpose and suitable for the user's method of application.		
Limitation of Remedies and Liability	If the 3M product is proved to be defective, THE EXCLUSIVE REMEDY, AT 3M'S OPTION, SHALL BE TO REFUND THE PURCHASE PRICE OF OR TO REPAIR OR REPLACE THE DEFECTIVE 3M PRODUCT. 3M shall not otherwise be liable for loss or damages, whether direct, indirect, special, incidental, or consequential, regardless of the legal theory asserted, including negligence, warranty or strict liability.		